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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# GA01PNS80-220

# Silicon Carbide PiN Diode

V <sub>RRM</sub>	=	8.0 kV
I <sub>F (Tc=25°C)</sub>	=	2 A

#### **Features**

- 8 kV blocking
- 175 °C operating temperature
- Fast turn off characteristics
- Soft reverse recovery characteristics
- Ultra-Fast high temperature switching

## **Package**

• RoHS Compliant



# **Advantages**

- · Reduced stacking
- Reduced system complexity/Increased reliability

### **Applications**

- Voltage Multiplier
- Ignition/Trigger Circuits
- Oil/Downhole
- Lighting
- Defense

#### Maximum Ratings at T<sub>i</sub> = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$		8	kV
Continuous forward current	l <sub>F</sub>		2	Α
RMS forward current	I <sub>F(RMS)</sub>		1	Α
Operating and storage temperature	$T_{j} \ ,  T_{stg}$		-55 to 175	°C

#### Electrical Characteristics at T<sub>j</sub> = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions		Values		Unit
		Conditions	min.	typ.	max.	Unit
Diode forward voltage	$V_{F}$	$I_F = 2 \text{ A}, T_j = 25 \text{ °C}$ $I_F = 2 \text{ A}, T_j = 175 \text{ °C}$		6.1 4.7		V
Reverse current	I <sub>R</sub>	$V_R = 8 \text{ kV}, T_j = 25 \text{ °C}$ $V_R = 8 \text{ kV}, T_j = 175 \text{ °C}$		4 4		μΑ
Total reverse recovery charge	Q <sub>rr</sub>	$I_F \le I_{F,MAX}$ $V_R = 1000$ $I_F = 1.5 A$ $V_R = 1000$		558		nC
Switching time	ts	$T_j = 175 \text{ °C}$ $V_R = 1000 $ $V_R = 1.5 \text{ A}$	V	< 236		ns
Total capacitance	С	$V_R = 1 \text{ V}, f = 1 \text{ MHz}, T_j = 25 \text{ °C}$ $V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25 \text{ °C}$ $V_R = 1000 \text{ V}, f = 1 \text{ MHz}, T_j = 25 \text{ °C}$		26 5 4		pF
Total capacitive charge	$Q_{C}$	V <sub>R</sub> = 1000 V, f = 1 MHz, T <sub>j</sub> = 25 °C	)	5.4		nC



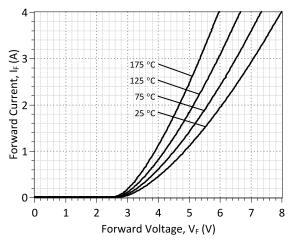


Figure 1: Typical Forward Characteristics

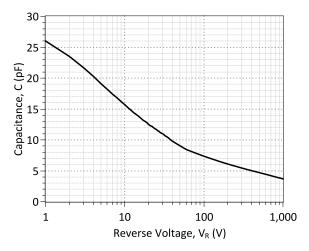


Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics

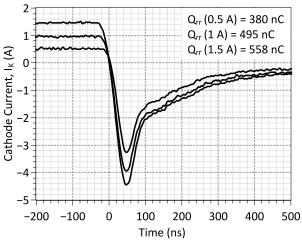


Figure 5: Typical Turn Off Characteristics at  $T_{\rm j}$  = 175°C and  $V_{\rm R}$  = 1000 V

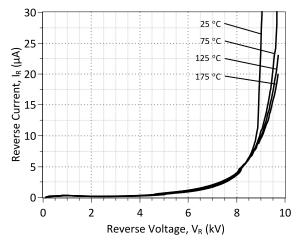


Figure 2: Typical Reverse Characteristics at 25°C

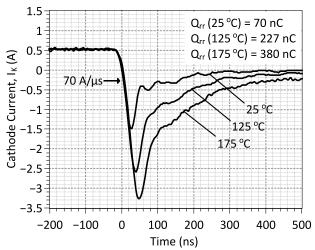


Figure 4: Typical Turn Off Characteristics at  $I_{\text{k}}$  = 0.5 A and  $V_{\text{R}}$  = 1000 V

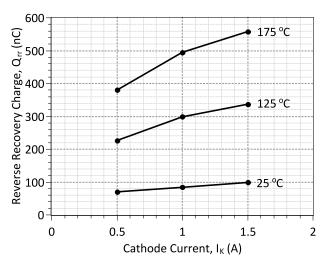


Figure 6: Reverse Recovery Charge vs Cathode Current

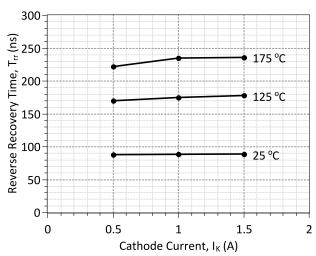
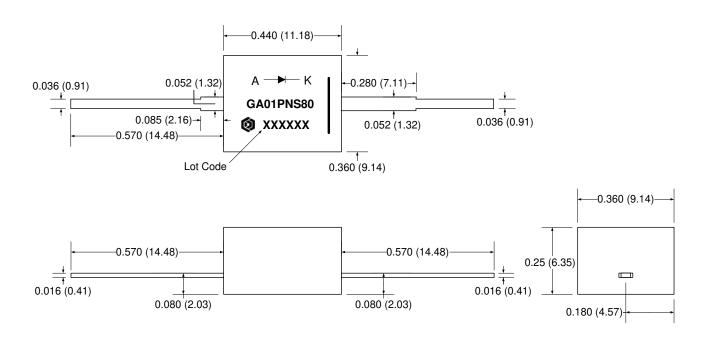


Figure 7: Reverse Recovery Time vs Cathode Current

#### **Package Dimensions:**

#### **PACKAGE OUTLINE**



#### NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
  2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS



# GA01PNS80-220

Revision History				
Date	Revision	Comments	Supersedes	
2015/04/30	1	Updated Electrical Characteristics		
2014/11/07	0	Initial release		

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#### **SPICE Model Parameters**

This is a secure document. Please copy this code from the SPICE model PDF file on our website (http://www.genesicsemi.com/images/products\_sic/thyristor/GA01PNS80-220\_SPICE.pdf) into LTSPICE (version 4) software for simulation of the GA01PNS80-220.

```
MODEL OF GeneSiC Semiconductor Inc.
     $Revision: 1.1
                                $
     $Date: 30-APR-2015
     GeneSiC Semiconductor Inc.
     43670 Trade Center Place Ste. 155
     Dulles, VA 20166
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* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
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* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
 Start of GA01PNS80-220 SPICE Model
. MODEL GA01PNS80 D
+ IS
     9.2491e-015
         1.02512
+ RS
          3.3373
+ N
+ IKF
         0.00011784
          3.23
+ EG
         25
+ XTI
+ TRS1
         -0.0024
+ CJO
          2.7E-11
+ VJ
          2.304
          0.376
+ M
+ FC
          0.5
+ BV
         8000
+ IBV
         1.00E-03
+ VPK
          8000
+ IAVE
+ TYPE
          SiC PiN
+ MFG
         GeneSiC Semi
```

\* End of GA01PNS80-220 SPICE Model